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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	80 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc620-04-ss

2.0 PIC16C62X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in the PIC16C62X Product Identification System section at the end of this data sheet. When placing orders, please use this page of the data sheet to specify the correct part number.

2.1 UV Erasable Devices

The UV erasable version, offered in CERDIP package, is optimal for prototype development and pilot programs. This version can be erased and reprogrammed to any of the Oscillator modes.

Microchip's PICSTART® and PRO MATE® programmers both support programming of the PIC16C62X.

Note:	Microchip does not recommend code protecting windowed devices.

2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers who need the flexibility for frequent code updates and small volume applications. In addition to the program memory, the configuration bits must also be programmed.

2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP programming service for factory production orders. This service is made available for users who chose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices, but with all EPROM locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your Microchip Technology sales office for more details.

2.4 Serialized Quick-Turnaround-Production℠ (SQTP℠) Devices

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number, which can serve as an entry-code, password or ID number.

3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC16C62X family can be attributed to a number of architectural features commonly found in RISC microprocessors. To begin with, the PIC16C62X uses a Harvard architecture, in which, program and data are accessed from separate memories using separate busses. This improves bandwidth over traditional von Neumann architecture, where program and data are fetched from the same memory. Separating program and data memory further allows instructions to be sized differently than 8-bit wide data word. Instruction opcodes are 14-bits wide making it possible to have all single word instructions. A 14-bit wide program memory access bus fetches a 14-bit instruction in a single cycle. A two-stage pipeline overlaps fetch and execution of instructions. Consequently, all instructions (35) execute in a single cycle (200 ns @ 20 MHz) except for program branches.

The PIC16C620(A) and PIC16CR620A address 512 x 14 on-chip program memory. The PIC16C621(A) addresses 1K x 14 program memory. The PIC16C622(A) addresses 2K x 14 program memory. All program memory is internal.

The PIC16C62X can directly or indirectly address its register files or data memory. All special function registers including the program counter are mapped in the data memory. The PIC16C62X has an orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any Addressing mode. This symmetrical nature and lack of ‘special optimal situations’ make programming with the PIC16C62X simple yet efficient. In addition, the learning curve is reduced significantly.

The PIC16C62X devices contain an 8-bit ALU and working register. The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between data in the working register and any register file.

The ALU is 8-bits wide and capable of addition, subtraction, shift and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. In two-operand instructions, typically one operand is the working register (W register). The other operand is a file register or an immediate constant. In single operand instructions, the operand is either the W register or a file register.

The W register is an 8-bit working register used for ALU operations. It is not an addressable register.

Depending on the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), and Zero (Z) bits in the STATUS register. The C and DC bits operate as a Borrow and Digit Borrow out bit, respectively, bit in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

A simplified block diagram is shown in Figure 3-1, with a description of the device pins in Table 3-1.

6.0 TIMER0 MODULE

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
- Interrupt on overflow from FFh to 00h
- Edge select for external clock

Figure 6-1 is a simplified block diagram of the Timer0 module.

Timer mode is selected by clearing the T0CS bit (OPTION<5>). In Timer mode, the TMR0 will increment every instruction cycle (without prescaler). If Timer0 is written, the increment is inhibited for the following two cycles (Figure 6-2 and Figure 6-3). The user can work around this by writing an adjusted value to TMR0.

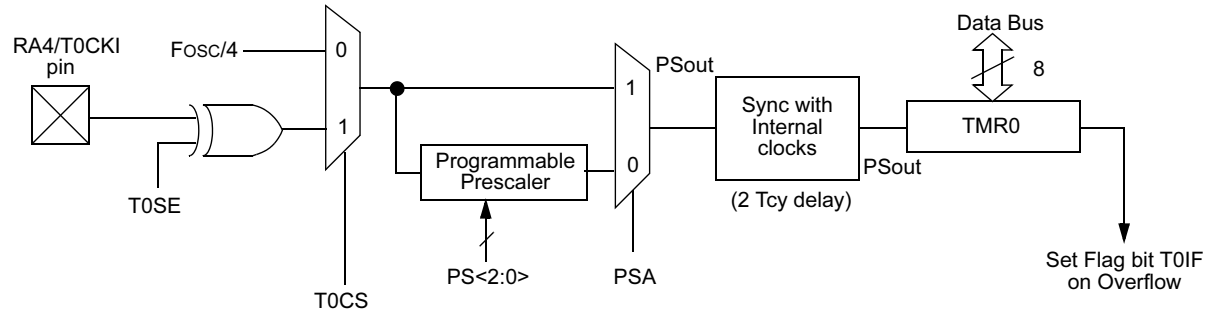
Counter mode is selected by setting the T0CS bit. In this mode, Timer0 will increment either on every rising or falling edge of pin RA4/T0CKI. The incrementing edge is determined by the source edge (T0SE) control bit (OPTION<4>). Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 6.2.

The prescaler is shared between the Timer0 module and the Watchdog Timer. The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale value of 1:2, 1:4, ..., 1:256 are selectable. Section 6.3 details the operation of the prescaler.

6.1 TIMER0 Interrupt

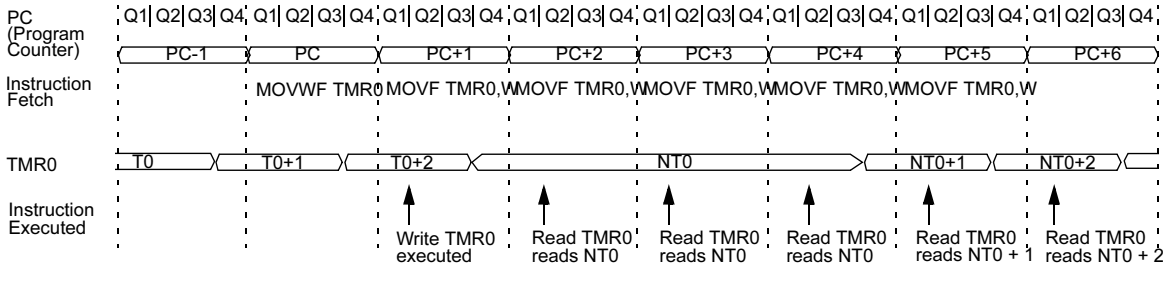
Timer0 interrupt is generated when the TMR0 register timer/counter overflows from FFh to 00h. This overflow sets the T0IF bit. The interrupt can be masked by clearing the T0IE bit (INTCON<5>). The T0IF bit (INTCON<2>) must be cleared in software by the Timer0 module interrupt service routine before re-enabling this interrupt. The Timer0 interrupt cannot wake the processor from SLEEP, since the timer is shut off during SLEEP. See Figure 6-4 for Timer0 interrupt timing.

FIGURE 6-1: TIMER0 BLOCK DIAGRAM



Note 1: Bits T0SE, T0CS, PS2, PS1, PS0 and PSA are located in the OPTION register.
2: The prescaler is shared with Watchdog Timer (Figure 6-6).

FIGURE 6-2: TIMER0 (TMR0) TIMING: INTERNAL CLOCK/NO PRESCALER



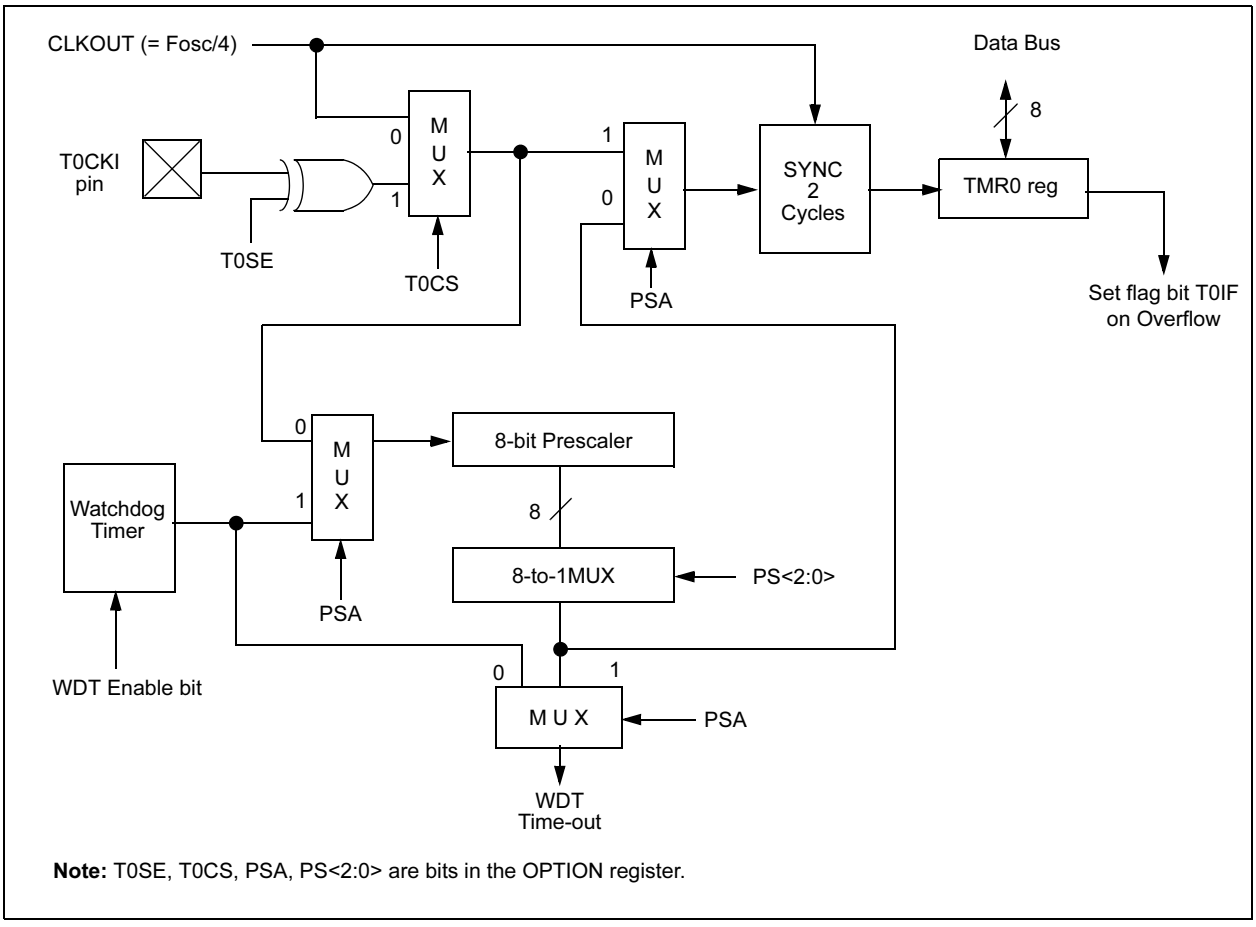
6.3 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscaler for the Watchdog Timer, respectively (Figure 6-6). For simplicity, this counter is being referred to as “prescaler” throughout this data sheet. Note that there is only one prescaler available which is mutually exclusive between the Timer0 module and the Watchdog Timer. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the Watchdog Timer and vice-versa.

The PSA and PS<2:0> bits (OPTION<3:0>) determine the prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., `CLRF 1`, `MOVWF 1`, `BSF 1,x`....etc.) will clear the prescaler. When assigned to WDT, a `CLRWDT` instruction will clear the prescaler along with the Watchdog Timer. The prescaler is not readable or writable.

FIGURE 6-6: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER



Note: T0SE, T0CS, PSA, PS<2:0> are bits in the OPTION register.

9.4 Power-on Reset (POR), Power-up Timer (PWRT), Oscillator Start-up Timer (OST) and Brown-out Reset (BOR)

9.4.1 POWER-ON RESET (POR)

The on-chip POR circuit holds the chip in RESET until VDD has reached a high enough level for proper operation. To take advantage of the POR, just tie the MCLR pin through a resistor to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A maximum rise time for VDD is required. See Electrical Specifications for details.

The POR circuit does not produce an internal RESET when VDD declines.

When the device starts normal operation (exits the RESET condition), device operating parameters (voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in RESET until the operating conditions are met.

For additional information, refer to Application Note AN607, “Power-up Trouble Shooting”.

9.4.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms (nominal) time-out on power-up only, from POR or Brown-out Reset. The Power-up Timer operates on an internal RC oscillator. The chip is kept in RESET as long as PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level. A configuration bit, PWRTE can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should always be enabled when Brown-out Reset is enabled.

The Power-up Time delay will vary from chip-to-chip and due to VDD, temperature and process variation. See DC parameters for details.

9.4.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-Up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

9.4.4 BROWN-OUT RESET (BOR)

The PIC16C62X members have on-chip Brown-out Reset circuitry. A configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V refer to VBOR parameter D005 (VBOR) for greater than parameter (TBOR) in Table 12-5. The brown-out situation will RESET the chip. A RESET won’t occur if VDD falls below 4.0V for less than parameter (TBOR).

On any RESET (Power-on, Brown-out, Watchdog, etc.) the chip will remain in RESET until VDD rises above BVDD. The Power-up Timer will now be invoked and will keep the chip in RESET an additional 72 ms.

If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be re-initialized. Once VDD rises above BVDD, the Power-Up Timer will execute a 72 ms RESET. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 9-7 shows typical Brown-out situations.

FIGURE 9-7: BROWN-OUT SITUATIONS

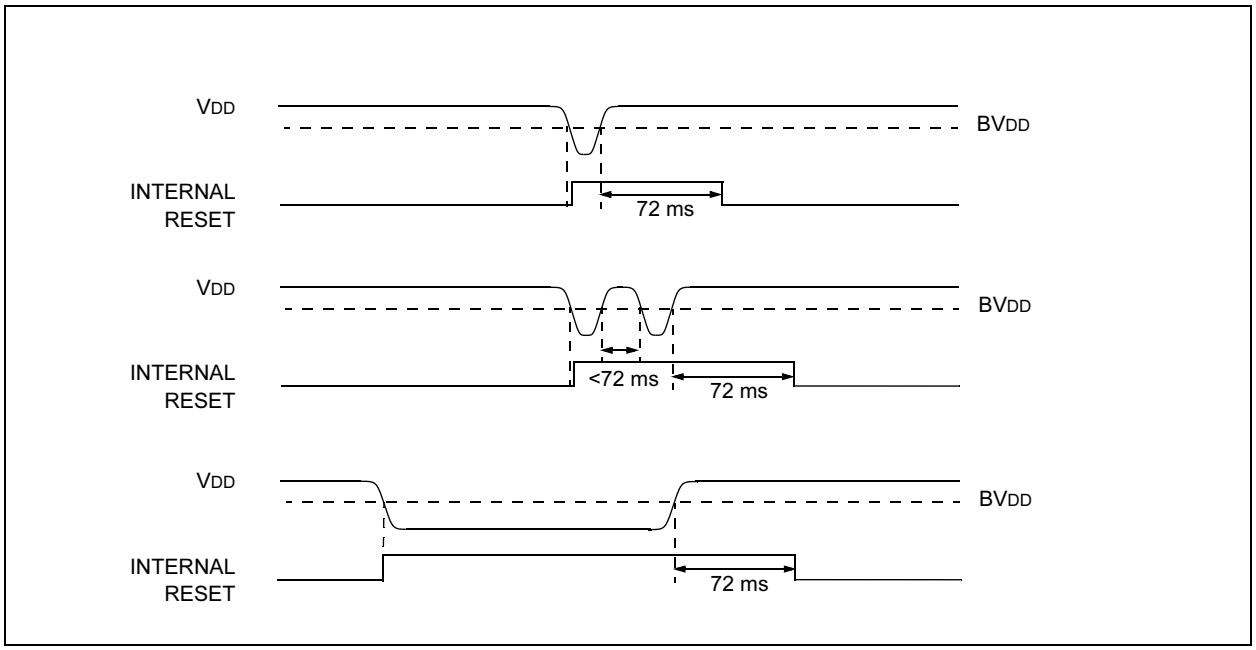


TABLE 10-2: PIC16C62X INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb			LSb	Status Affected	Notes
BYTE-ORIENTED FILE REGISTER OPERATIONS									
ADDWF	**f, d**	Add W and f	1	00	0111	dfff	ffff	C,DC,Z	1,2
ANDWF	**f, d**	AND W with f	1	00	0101	dfff	ffff	Z	1,2
CLRF	**f**	Clear f	1	00	0001	lfff	ffff	Z	2
CLRW	**-**	Clear W	1	00	0001	0000	0011	Z	
COMF	**f, d**	Complement f	1	00	1001	dfff	ffff	Z	1,2
DECF	**f, d**	Decrement f	1	00	0011	dfff	ffff	Z	1,2
DECFSZ	**f, d**	Decrement f, Skip if 0	1(2)	00	1011	dfff	ffff		1,2,3
INCF	**f, d**	Increment f	1	00	1010	dfff	ffff	Z	1,2
INCFSZ	**f, d**	Increment f, Skip if 0	1(2)	00	1111	dfff	ffff		1,2,3
IORWF	**f, d**	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1,2
MOVF	**f, d**	Move f	1	00	1000	dfff	ffff	Z	1,2
MOVWF	**f**	Move W to f	1	00	0000	lfff	ffff		
NOP	**-**	No Operation	1	00	0000	0xx0	0000		
RLF	**f, d**	Rotate Left f through Carry	1	00	1101	dfff	ffff	C	1,2
RRF	**f, d**	Rotate Right f through Carry	1	00	1100	dfff	ffff	C	1,2
SUBWF	**f, d**	Subtract W from f	1	00	0010	dfff	ffff	C,DC,Z	1,2
SWAPF	**f, d**	Swap nibbles in f	1	00	1110	dfff	ffff		1,2
XORWF	**f, d**	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1,2
BIT-ORIENTED FILE REGISTER OPERATIONS									
BCF	**f, b**	Bit Clear f	1	01	00bb	bfff	ffff		1,2
BSF	**f, b**	Bit Set f	1	01	01bb	bfff	ffff		1,2
BTFSC	**f, b**	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	**f, b**	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		3
LITERAL AND CONTROL OPERATIONS									
ADDLW	**k**	Add literal and W	1	11	111x	kkkk	kkkk	C,DC,Z	
ANDLW	**k**	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	**k**	Call subroutine	2	10	0kkk	kkkk	kkkk		
CLRWDT	**-**	Clear Watchdog Timer	1	00	0000	0110	0100	$\overline{TO}$,$\overline{PD}$	
GOTO	**k**	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	**k**	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	**k**	Move literal to W	1	11	00xx	kkkk	kkkk		
RETFIE	**-**	Return from interrupt	2	00	0000	0000	1001		
RETLW	**k**	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETURN	**-**	Return from Subroutine	2	00	0000	0000	1000		
SLEEP	**-**	Go into Standby mode	1	00	0000	0110	0011	$\overline{TO}$,$\overline{PD}$	
SUBLW	**k**	Subtract W from literal	1	11	110x	kkkk	kkkk	C,DC,Z	
XORLW	**k**	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	

Note 1: When an I/O register is modified as a function of itself (e.g., `MOVF PORTB, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.

3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a `NOP`.

CLRW **Clear W**

Syntax: [*label*] CLRW

Operands: None

Operation: 00h → (W)
1 → Z

Status Affected: Z

Encoding:

00	0001	0000	0011

Description: W register is cleared. Zero bit (Z) is set.

Words: 1

Cycles: 1

Example
```
CLRW
```
Before Instruction
W = 0x5A
After Instruction
W = 0x00
Z = 1

CLRWDT **Clear Watchdog Timer**

Syntax: [*label*] CLRWDT

Operands: None

Operation: 00h → WDT
0 → WDT prescaler,
1 → $\overline{TO}$
1 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

00	0000	0110	0100

Description: CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. STATUS bits $\overline{TO}$ and $\overline{PD}$ are set.

Words: 1

Cycles: 1

Example
```
CLRWDT
```
Before Instruction
WDT counter = ?
After Instruction
WDT counter = 0x00
WDT prescaler = 0
$\overline{TO}$ = 1
$\overline{PD}$ = 1

COMF **Complement f**

Syntax: [*label*] COMF f,d

Operands: 0 ≤ f ≤ 127
d ∈ [0,1]

Operation: ($\bar{f}$) → (dest)

Status Affected: Z

Encoding:

00	1001	dfff	ffff

Description: The contents of register 'f' are complemented. If 'd' is 0, the result is stored in W. If 'd' is 1, the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
COMF    REG1,0
```
Before Instruction
REG1 = 0x13
After Instruction
REG1 = 0x13
W = 0xEC

DECF **Decrement f**

Syntax: [*label*] DECF f,d

Operands: 0 ≤ f ≤ 127
d ∈ [0,1]

Operation: (f) - 1 → (dest)

Status Affected: Z

Encoding:

00	0011	dfff	ffff

Description: Decrement register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example
```
DECF    CNT, 1
```
Before Instruction
CNT = 0x01
Z = 0
After Instruction
CNT = 0x00
Z = 1

RLF **Rotate Left f through Carry**

Syntax: [*label*] RLF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

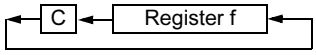
Operation: See description below

Status Affected: C

Encoding:

00	1101	dfff	ffff

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is stored back in register 'f'.



Words: 1

Cycles: 1

Example

```
RLF     REG1,0
```

Before Instruction

```
REG1    =   1110 0110
C       =   0
```

After Instruction

```
REG1    =   1110 0110
W       =   1100 1100
C       =   1
```

RRF **Rotate Right f through Carry**

Syntax: [*label*] RRF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

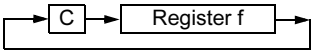
Operation: See description below

Status Affected: C

Encoding:

00	1100	dfff	ffff

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.



Words: 1

Cycles: 1

Example

```
RRF         REG1,
            0
```

Before Instruction

```
REG1    =   1110 0110
C       =   0
```

After Instruction

```
REG1    =   1110 0110
W       =   0111 0011
C       =   0
```

SLEEP

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h → WDT,
0 → WDT prescaler,
1 → $\overline{TO}$,
0 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

00	0000	0110	0011

Description: The power-down STATUS bit, $\overline{PD}$ is cleared. Time-out STATUS bit, $\overline{TO}$ is set. Watch-dog Timer and its prescaler are cleared.
The processor is put into SLEEP mode with the oscillator stopped. See Section 9.8 for more details.

Words: 1

Cycles: 1

Example:

```
SLEEP
```

11.0 DEVELOPMENT SUPPORT

The PICmicro® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
  - MPASM™ Assembler
  - MPLAB C17 and MPLAB C18 C Compilers
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB C30 C Compiler
  - MPLAB ASM30 Assembler/Linker/Library
- Simulators
  - MPLAB SIM Software Simulator
  - MPLAB dsPIC30 Software Simulator
- Emulators
  - MPLAB ICE 2000 In-Circuit Emulator
  - MPLAB ICE 4000 In-Circuit Emulator
- In-Circuit Debugger
  - MPLAB ICD 2
- Device Programmers
  - PRO MATE® II Universal Device Programmer
  - PICSTART® Plus Development Programmer
- Low Cost Demonstration Boards
  - PICDEM™ 1 Demonstration Board
  - PICDEM.net™ Demonstration Board
  - PICDEM 2 Plus Demonstration Board
  - PICDEM 3 Demonstration Board
  - PICDEM 4 Demonstration Board
  - PICDEM 17 Demonstration Board
  - PICDEM 18R Demonstration Board
  - PICDEM LIN Demonstration Board
  - PICDEM USB Demonstration Board
- Evaluation Kits
  - KEELOQ®
  - PICDEM MSC
  - microID®
  - CAN
  - PowerSmart®
  - Analog

11.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16-bit microcontroller market. The MPLAB IDE is a Windows® based application that contains:

- An interface to debugging tools
  - simulator
  - programmer (sold separately)
  - emulator (sold separately)
  - in-circuit debugger (sold separately)
- A full-featured editor with color coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High level source code debugging
- Mouse over variable inspection
- Extensive on-line help

The MPLAB IDE allows you to:

- Edit your source files (either assembly or C)
- One touch assemble (or compile) and download to PICmicro emulator and simulator tools (automatically updates all project information)
- Debug using:
  - source files (assembly or C)
  - absolute listing file (mixed assembly and C)
  - machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost effective simulators, through low cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increasing flexibility and power.

11.2 MPASM Assembler

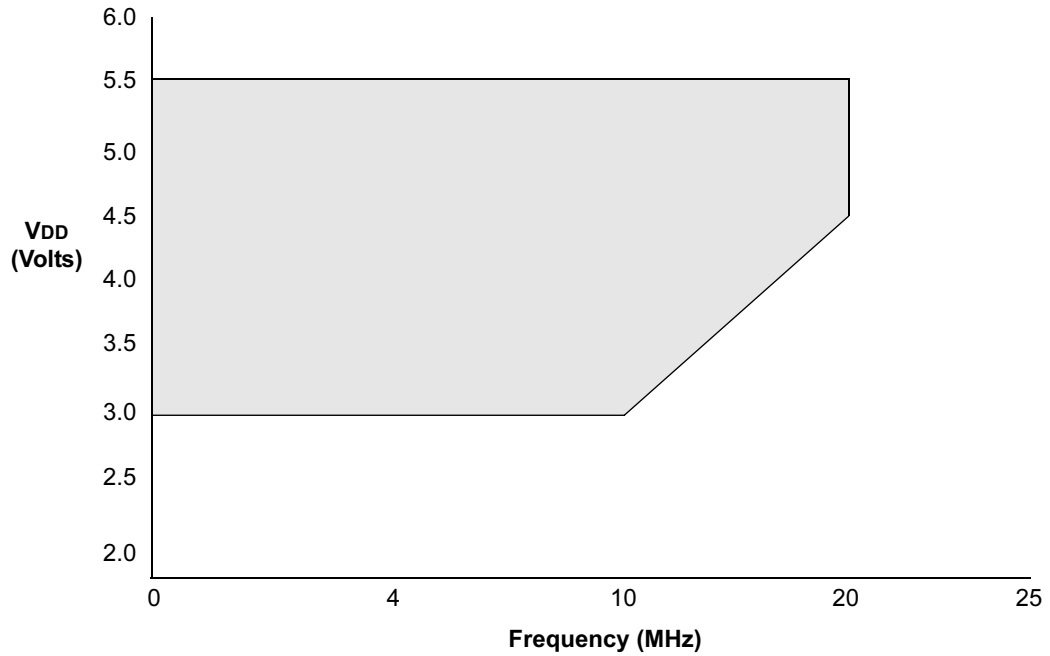
The MPASM assembler is a full-featured, universal macro assembler for all PICmicro MCUs.

The MPASM assembler generates relocatable object files for the MPLINK object linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM assembler features include:

- Integration into MPLAB IDE projects
- User defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

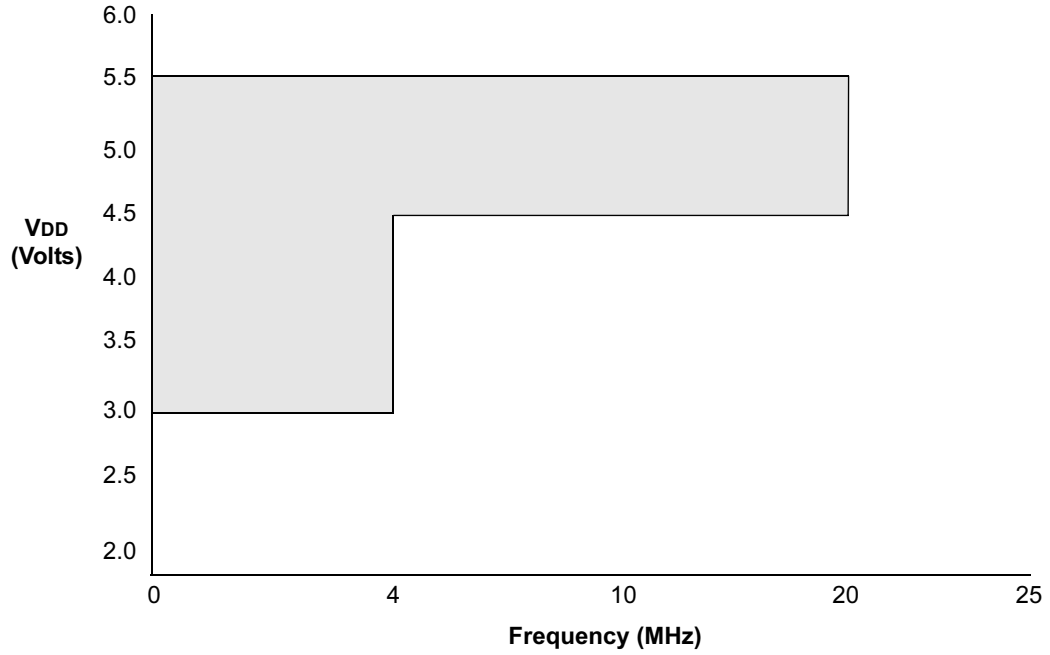
FIGURE 12-3: PIC16C62XA VOLTAGE-FREQUENCY GRAPH, 0°C ≤ TA ≤ +70°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

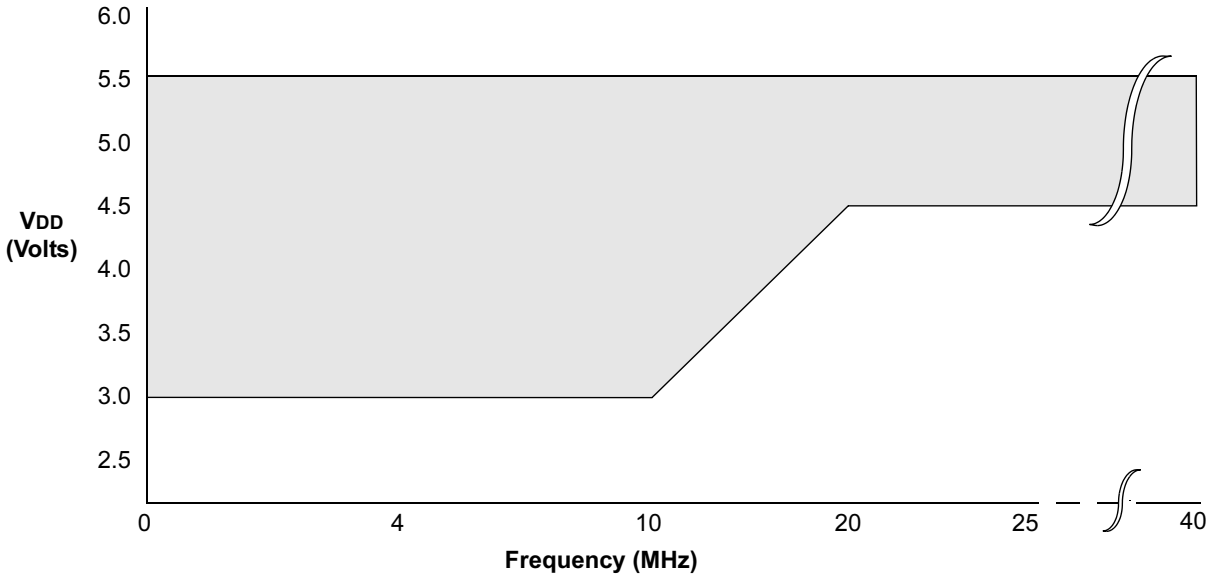
FIGURE 12-4: PIC16C62XA VOLTAGE-FREQUENCY GRAPH, -40°C ≤ TA ≤ 0°C, +70°C ≤ TA ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

FIGURE 12-10: PIC16C620A/C621A/C622A/CR620A - 40 VOLTAGE-FREQUENCY GRAPH, 0°C ≤ TA ≤ +70°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

3: Operation between 20 to 40 MHz requires the following:

- VDD between 4.5V. and 5.5V
- OSC1 externally driven
- OSC2 not connected
- HS mode
- Commercial temperatures

Devices qualified for 40 MHz operation have -40 designation (ex: PIC16C620A-40/P).

12.1 DC Characteristics: PIC16C62X-04 (Commercial, Industrial, Extended) PIC16C62X-20 (Commercial, Industrial, Extended) PIC16LC62X-04 (Commercial, Industrial, Extended)

PIC16C62X	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended
PIC16LC62X	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended Operating voltage VDD range is the PIC16C62X range.

Param. No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	3.0	—	6.0	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5
D001	VDD	Supply Voltage	2.5	—	6.0	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5
D002	VDR	RAM Data Retention Voltage(1)	—	1.5*	—	V	Device in SLEEP mode
D002	VDR	RAM Data Retention Voltage(1)	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	Vss	—	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	VSS	—	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	—	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.3	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.3	V	BOREN configuration bit is cleared
D010	IDD	Supply Current(2)	—	1.8	3.3	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, (**Note 4**)*
			—	35	70	µA	FOSC = 32 kHz, VDD = 4.0V, WDT disabled, LP mode
			—	9.0	20	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled, HS mode
D010	IDD	Supply Current(2)	—	1.4	2.5	mA	FOSC = 2.0 MHz, VDD = 3.0V, WDT disabled, XT mode, (**Note 4**)
			—	26	53	µA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode
D020	IPD	Power-down Current(3)	—	1.0	2.5 15	µA µA	VDD=4.0V, WDT disabled (125°C)
D020	IPD	Power-down Current(3)	—	0.7	2	µA	VDD=3.0V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in Active Operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

PIC16CR62XA-04 **PIC16CR62XA-20**			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
PIC16LCR62XA-04			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in Active Operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

12.8 Timing Parameter Symbology

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

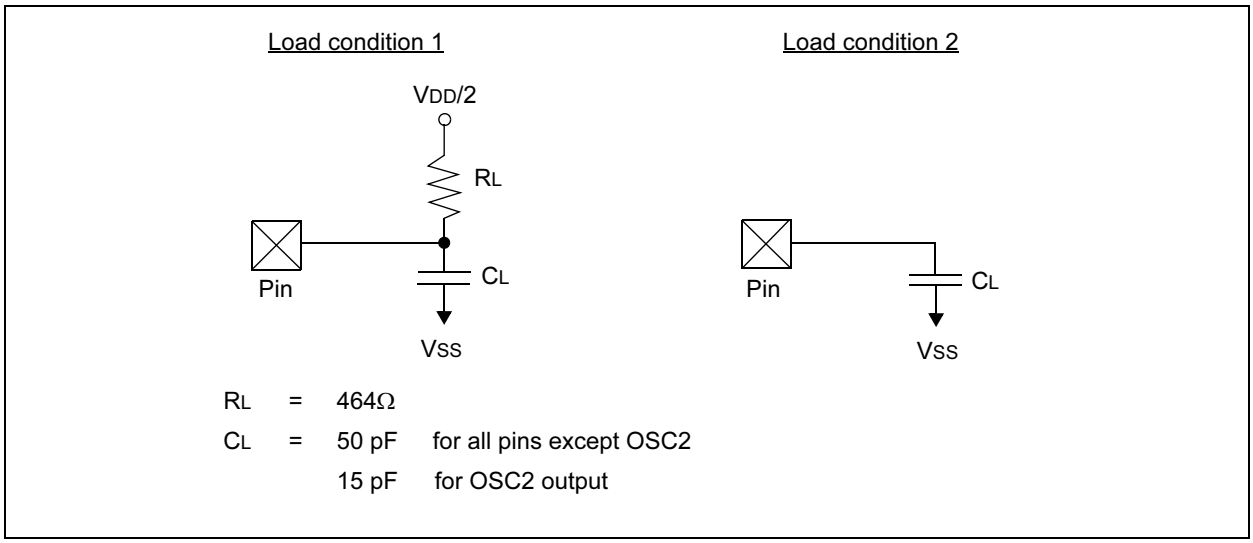
Lowercase subscripts (pp) and their meanings:

pp			
ck	CLKOUT	osc	OSC1
io	I/O port	t0	T0CKI
mc	$\overline{\text{MCLR}}$		

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-Impedance

FIGURE 12-11: LOAD CONDITIONS



12.9 Timing Diagrams and Specifications

FIGURE 12-12: EXTERNAL CLOCK TIMING

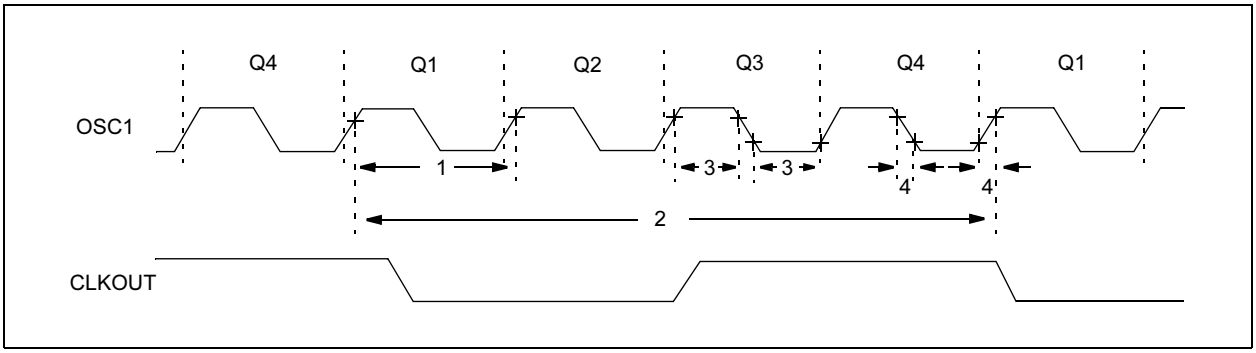


TABLE 12-3: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
1A	Fosc	External CLKIN Frequency(1)	DC	—	4	MHz	XT and RC Osc mode, VDD=5.0V
			DC	—	20	MHz	HS Osc mode
			DC	—	200	kHz	LP Osc mode
		Oscillator Frequency(1)	DC	—	4	MHz	RC Osc mode, VDD=5.0V
			0.1	—	4	MHz	XT Osc mode
			1	—	20	MHz	HS Osc mode
			DC	—	200	kHz	LP Osc mode
1	Tosc	External CLKIN Period(1)	250	—	—	ns	XT and RC Osc mode
			50	—	—	ns	HS Osc mode
			5	—	—	µs	LP Osc mode
		Oscillator Period(1)	250	—	—	ns	RC Osc mode
			250	—	10,000	ns	XT Osc mode
			50	—	1,000	ns	HS Osc mode
			5	—	—	µs	LP Osc mode
2	TCY	Instruction Cycle Time(1)	1.0	FOSC/4	DC	µs	TCYS=FOSC/4
3*	TosL, TosH	External Clock in (OSC1) High or Low Time	100*	—	—	ns	XT oscillator, TOSC L/H duty cycle
			2*	—	—	µs	LP oscillator, TOSC L/H duty cycle
			20*	—	—	ns	HS oscillator, TOSC L/H duty cycle
4*	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	25*	—	—	ns	XT oscillator
			50*	—	—	ns	LP oscillator
			15*	—	—	ns	HS oscillator

2: * These parameters are characterized but not tested.

3: † Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1 pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 12-14: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

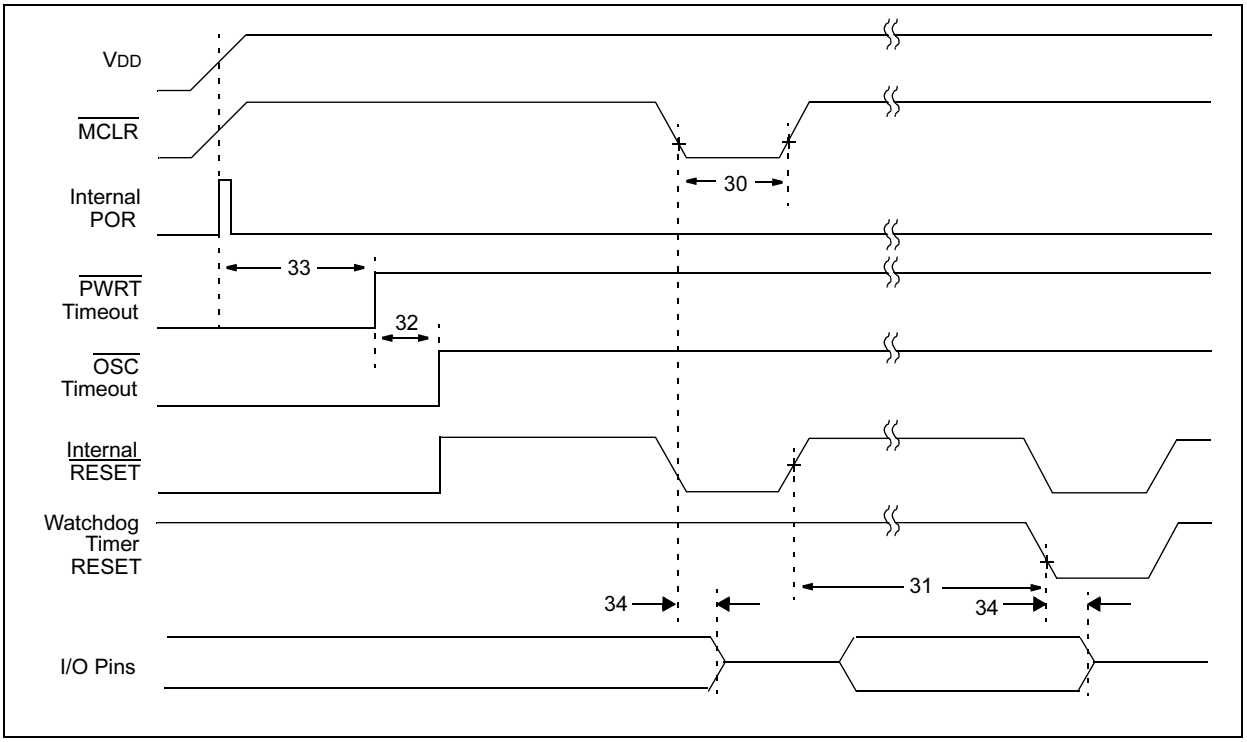


FIGURE 12-15: BROWN-OUT RESET TIMING

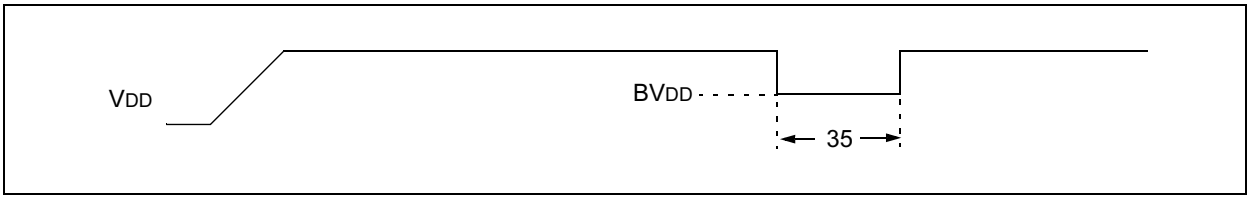


TABLE 12-5: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{\text{MCLR}}$ Pulse Width (low)	2000	—	—	ns	-40° to +85°C
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7*	18	33*	ms	VDD = 5.0V, -40° to +85°C
32	Tost	Oscillation Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period
33	Tpwrt	Power-up Timer Period	28*	72	132*	ms	VDD = 5.0V, -40° to +85°C
34	TIOZ	I/O hi-impedance from $\overline{\text{MCLR}}$ low		—	2.0	µs	
35	TBOR	Brown-out Reset Pulse Width	100*	—	—	µs	3.7V ≤ VDD ≤ 4.3V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 12-16: TIMER0 CLOCK TIMING

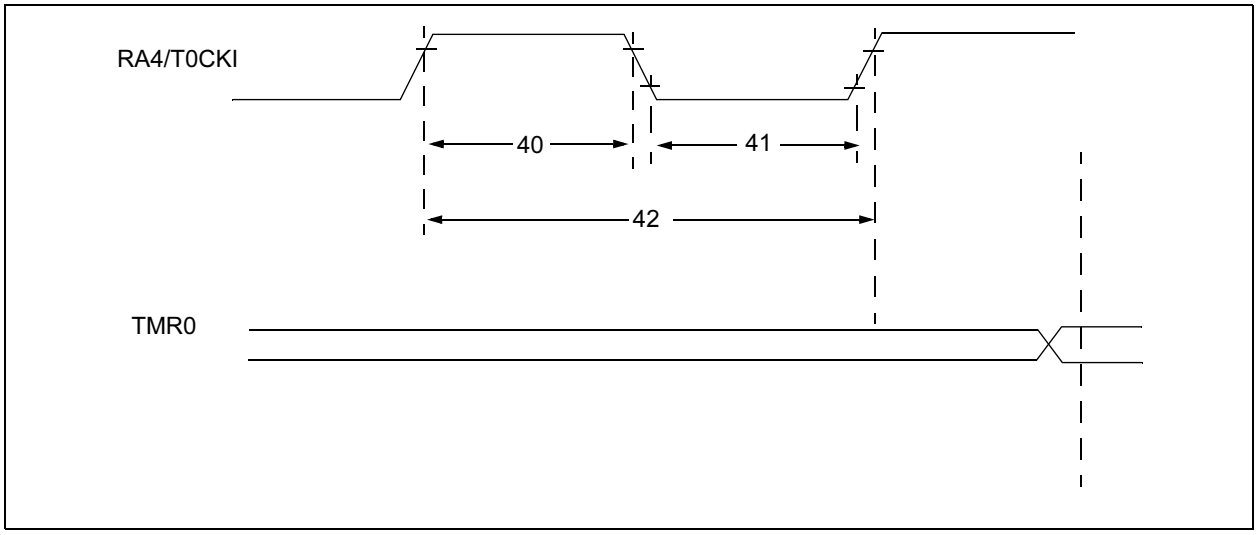


TABLE 12-6: TIMER0 CLOCK REQUIREMENTS

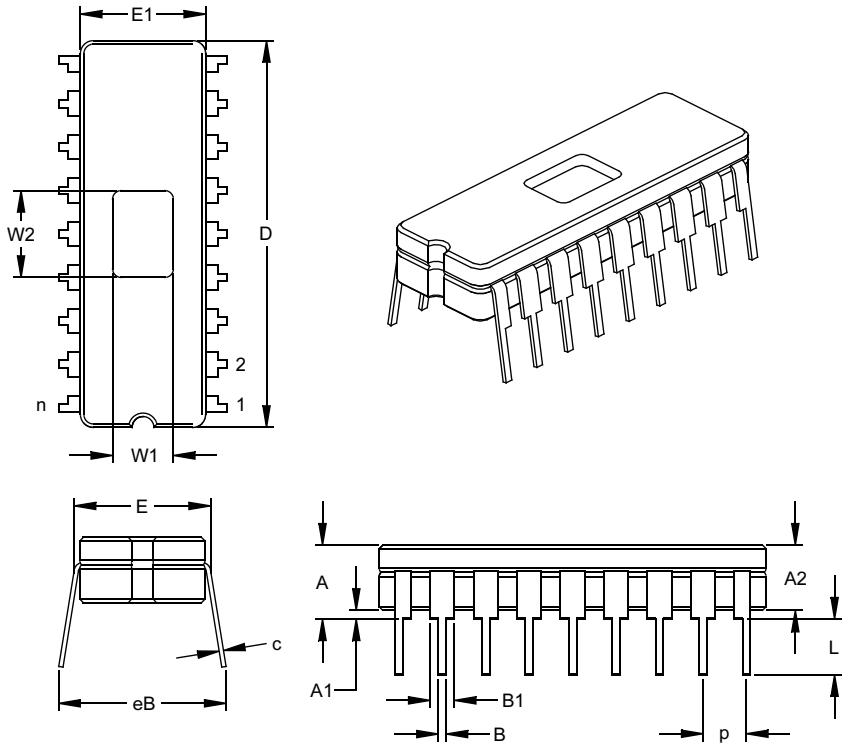
Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5 TCY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5 TCY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period		TCY + 40* N	—	—	ns	N = prescale value (1, 2, 4, ..., 256)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

14.0 PACKAGING INFORMATION

18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing §	eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

* Controlling Parameter
§ Significant Characteristic
JEDEC Equivalent: MO-036
Drawing No. C04-010

NOTES:

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